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EMC IC modelling –
Part 3: Models of integrated circuits for EMI behavioural simulation – Radiated emissions modelling (ICEM-RE)

Modèles de circuits intégrés pour la CEM –
Partie 3: Modèles de circuits intégrés pour la simulation du comportement lors de perturbations électromagnétiques – Modélisation des émissions rayonnées (ICEM-RE)

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EMC IC MODELLING –

Part 3: Models of integrated circuits for EMI behavioural simulation – Radiated emissions modelling (ICEM-RE)

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FDIS	Report on voting
47A/1000/FDIS	47A/1008/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62433 series, published under the general title *EMC IC modelling*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

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EMC IC MODELLING –

Part 3: Models of integrated circuits for EMI behavioural simulation – Radiated emissions modelling (ICEM-RE)

1 Scope

This part of IEC 62433 provides a method for deriving a macro-model to allow the simulation of the radiated emission levels of an Integrated Circuit (IC). This model is commonly called Integrated Circuit Emission Model – Radiated Emission, ICEM-RE. The model is intended to be used for modelling a complete IC, with or without its associated package, a functional block and an Intellectual Property (IP) block of both analogue and digital ICs (input/output pins, digital core and supply), when measured or simulated data cannot be directly imported into simulation tools.

The proposed IC macro-model will be inserted in 3D electromagnetic simulation tools so as to:

- predict the near-radiated emissions from the IC
- evaluate the effect of the radiated emissions on neighbouring ICs, cables, transmission lines, etc.

This part of IEC 62433 has two main parts:

- the first is the electrical description of ICEM-RE macro-model elements,
- the second part proposes a universal data exchange format called REML based on XML. This format allows encoding the ICEM-RE in a more useable and generic form for emission simulation.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC TS 62433-1, *EMC IC modelling – Part 1: General modelling framework*

IEC 62433-2, *EMC IC modelling – Part 2: Models of integrated circuits for EMI behavioural simulation – Conducted emissions modelling (ICEM-CE)*

IEC 61967-1, *Integrated circuits – Measurement of electromagnetic emissions, 150 kHz to 1 GHz – Part 1: General conditions and definitions*

IEC TS 61967-3, *Integrated circuits – Measurement of electromagnetic emissions – Part 3: Measurement of radiated emissions – Surface scan method*

ANSI INCITS 4:1986, *Information Systems – Coded Character Sets – 7-Bit American National Standard Code for Information Interchange (7-Bit ASCII)*